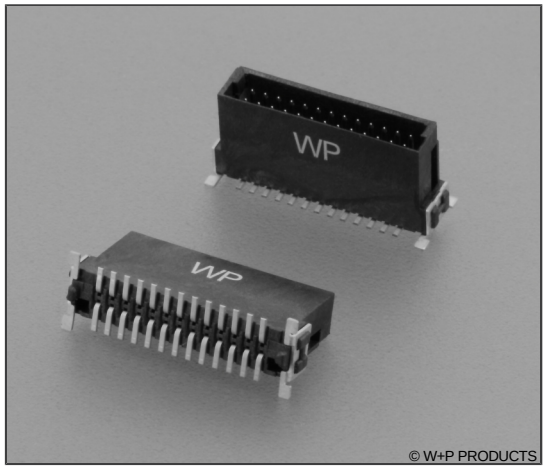
9015

SMT-Stiftleiste RM 1,27mm, stehend

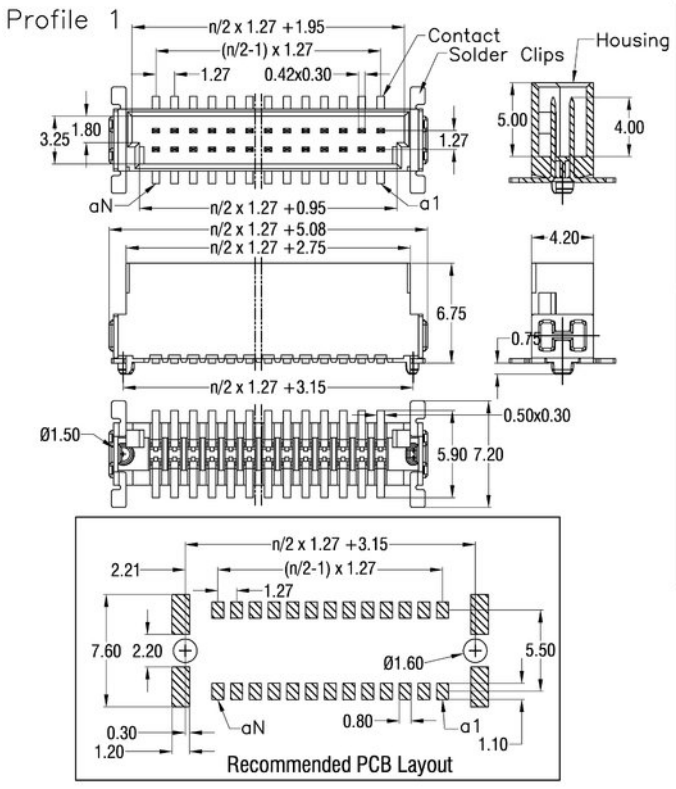
SMT Male Connector 1,27mm Pitch, vertical

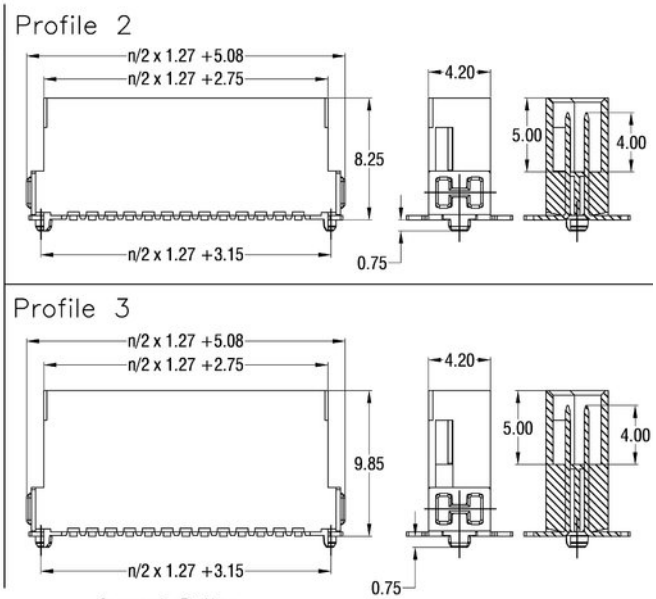
Technische Daten / ***Technical Data***

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	*Acc. to plating options, over Ni*
Durchgangswiderstand	< 25 mΩ
Contact Resistance	*< 25 mΩ*
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	*> 1000 MΩ*
Spannungsfestigkeit	500 V AC
Test Voltage	*500 V AC*
Temperaturbereich	-55 °C ... +125 °C
Temperature Range	*-55 °C ... +125 °C*
Verarbeitung	Reflow-Lötverfahren
Processing	*Reflow soldering*



Gegenstecker / *Mating Connectors*:
9012 9013





Current Rating :

No of pos	Ambient Temp 20°C	70°C	100°C
12	1.6A	1.1A	0.7A
26	1.3A	0.9A	0.6A
50	1.1A	0.8A	0.5A
68	1.0A	0.8A	0.5A
80	1.0A	0.8A	0.5A

Series	***Contacts****	***Profile****	***Plating****	***Packaging****
9015	**50**	**1**	**80**	**PPTR**
	12 26 50 68 80 Weitere Polzahlen auf Anfrage *More contact options on request*	**1** H=6.75mm **2** H=8.25mm **3** H=9.85mm	**60** Sel. Au flash / Sn **80** Sel. Au 30µ" / Sn	**ST** **TR** **PPST** **PPTR**

Übersicht über Bauhöhen in den technischen Informationen
Mating Height Chart under technical information

Lieferformen / ***Packaging Options:***
ST In Stangen ohne Pick&Place-Pads / *In tubes w/o Pick&Place-Pads*
TR Tape & Reel ohne PP-Pads / *Tape & Reel w/o PP-Pads*
PPST In Stangen mit PP-Pads / *In tubes with PP-Pads*
PPTR Tape & Reel mit PP-Pads / *Tape & Reel with PP-Pads*

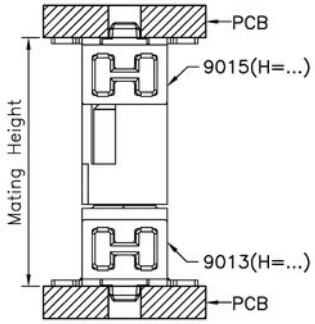
* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

9012 9013 9014 9015

Übersicht über die erreichbaren Bauhöhen

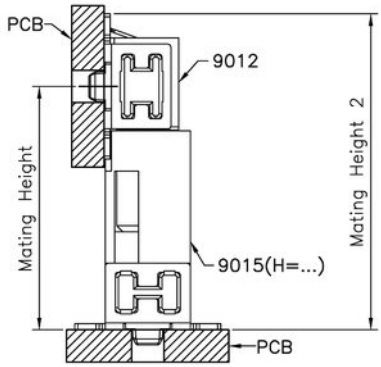
Chart of Attainable Mating Heights

9013 + 9015



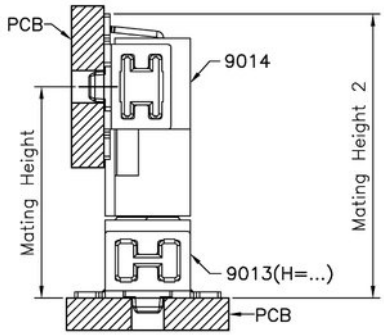
Mating Height		9015		
		H=6.75mm	H=8.25mm	H=9.85mm
9013	H=6.25mm	8.0 - 9.5	9.5 - 11.0	11. - 12.6
	H=9.05mm	10.8 - 12.3	12.3 - 13.8	13.9 - 15.4
	H=13.65mm	15.4 - 16.9	16.9 - 18.4	18.5 - 20.0

9012 + 9015



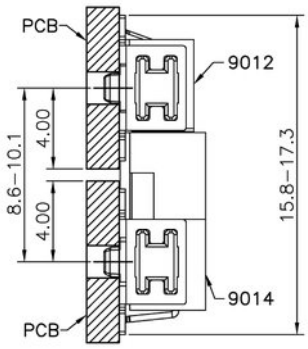
Mating Heights	9015		
	H=6.75mm	H=8.25mm	H=9.85mm
9012	8.95 - 10.45 12.55 - 14.05	10.45 - 11.95 14.05 - 15.55	12.05 - 13.55 15.65 - 17.15

9013 + 9014



Mating Heights	9013		
	H=6.25mm	H=9.05mm	H=13.65mm
9014	7.65 - 9.15 11.25 - 12.75	10.45 - 11.95 14.05 - 15.55	15.05 - 16.55 18.65 - 20.15

9012 + 9014



Reflow-Lötempfehlung
Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150 °C
Temperatur Maximum $T_S$max	200 °C
Dauer $T_S$min – $T_S$max	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_S$max – T_P	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_P$max – $T_S$min	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	**Key Values**
Minimum Temperature $T_S$min	*150 °C*
Maximum Temperatur $T_S$max	*200 °C*
Duration $T_S$min – $T_S$max	*60 – 180s*
Soldering Range Temperature T_L	*217 °C*
Duration above T_L	*60 – 180s*
Ramp-Up Rate $T_S$max – T_P	*max. 3 °C / s*
Peak Temperature T_P	*260±5 °C*
Duration Peak Temperature	*20 – 40s*
Ramp-Down Rate $T_P$max – $T_S$min	*6 °C / s*
Duration 25°C - Peak Temp. T_P	*max. 8min*